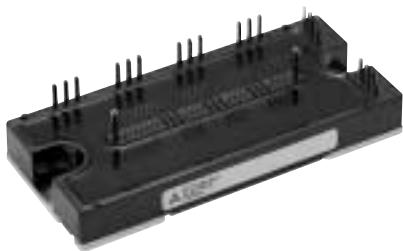


MITSUBISHI <INTELLIGENT POWER MODULES>

# PM50B6LB060

## **FLAT-BASE TYPE INSULATED PACKAGE**

**PM50B6LB060**



## FEATURE

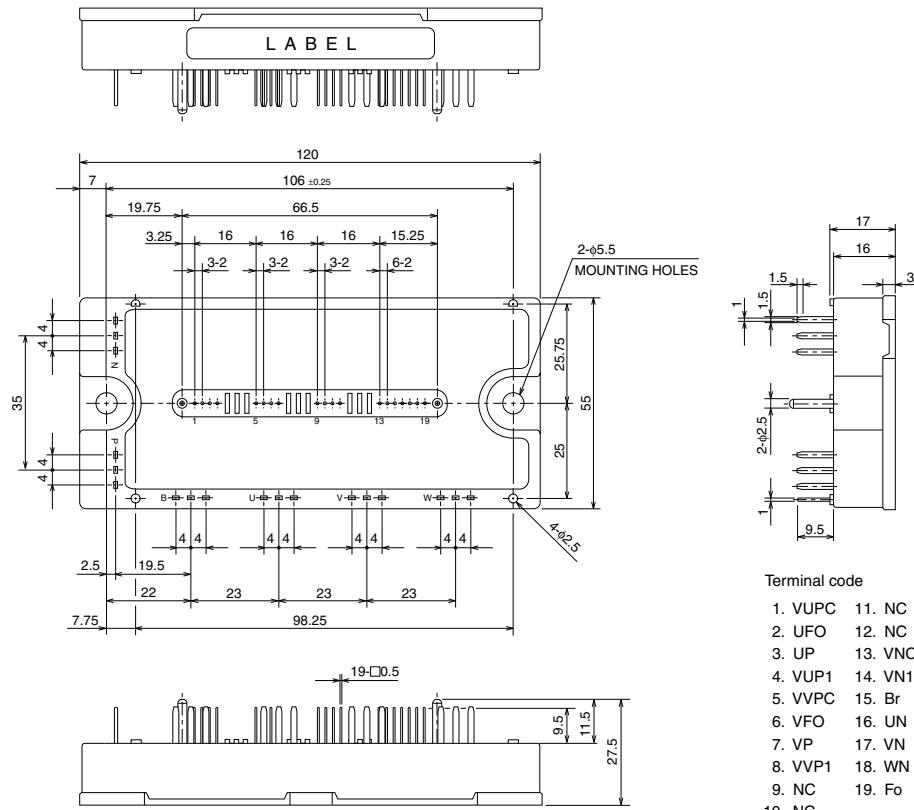
- a) Adopting new 5th generation IGBT (CSTBT™) chip, which performance is improved by  $1\mu\text{m}$  fine rule process.  
For example, typical  $V_{\text{ce}}(\text{sat})=1.55\text{V}$  @ $T_j=125^\circ\text{C}$
  - b) Over-temperature protection by detecting  $T_j$  of the CSTBT™ chips and error output is possible from all each conservation upper and lower arm of IPM.
  - c) New small package  
Reduce the package size by 10%, thickness by 22% from S-DASH series.
    - 2φ 50A, 600V Current-sense IGBT type inverter
    - 50A, 600V Current-sense Chopper IGBT
    - Monolithic gate drive & protection logic
    - Detection, protection & status indication circuits for, short-circuit, over-temperature & under-voltage (P-Fo available from upper arm devices)
    - UL Recognized Yellow Card No.E80276(N)

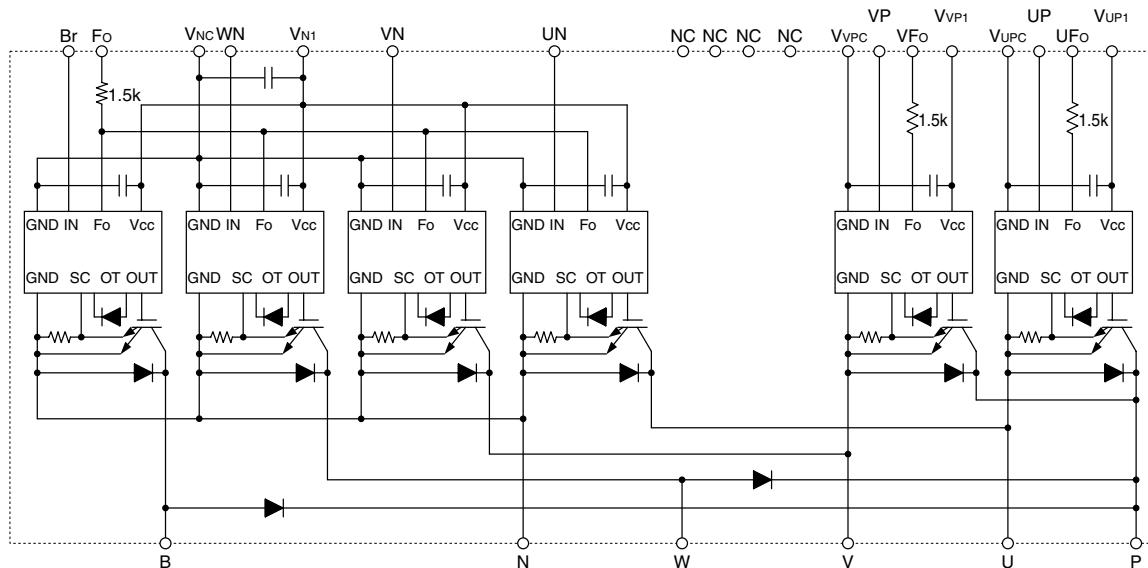
## APPLICATION

## Photo voltaic power conditioner

## PACKAGE OUTLINES

### **Dimensions in mm**



**PM50B6LB060**FLAT-BASE TYPE  
INSULATED PACKAGE**INTERNAL FUNCTIONS BLOCK DIAGRAM****MAXIMUM RATINGS** ( $T_j = 25^\circ\text{C}$ , unless otherwise noted)**INVERTER PART**

Symbol	Parameter	Condition	Ratings	Unit
V <sub>CES</sub>	Collector-Emitter Voltage	$V_D = 15\text{V}$ , $V_{CIN} = 15\text{V}$	600	V
$\pm I_C$	Collector Current	$T_C = 25^\circ\text{C}$	50	A
$\pm I_{CP}$	Collector Current (Peak)	$T_C = 25^\circ\text{C}$	100	A
P <sub>C</sub>	Collector Dissipation	$T_C = 25^\circ\text{C}$	131	W
T <sub>j</sub>	Junction Temperature		-20 ~ +150	°C

**CONVERTER PART**

Symbol	Parameter	Condition	Ratings	Unit
V <sub>CES</sub>	Collector-Emitter Voltage	$V_D = 15\text{V}$ , $V_{CIN} = 15\text{V}$	600	V
I <sub>C</sub>	Collector Current	$T_C = 25^\circ\text{C}$	50	A
I <sub>CP</sub>	Collector Current (Peak)	$T_C = 25^\circ\text{C}$	100	A
P <sub>C</sub>	Collector Dissipation	$T_C = 25^\circ\text{C}$	(Note-1) 131	W
I <sub>F</sub>	FWD <sub>i</sub> Forward Current	$T_C = 25^\circ\text{C}$	50	A
V <sub>R(DC)</sub>	FWD <sub>i</sub> Rated DC Reverse Voltage	$T_C = 25^\circ\text{C}$	600	V
T <sub>j</sub>	Junction Temperature		-20 ~ +150	°C

**CONTROL PART**

Symbol	Parameter	Condition	Ratings	Unit
V <sub>D</sub>	Supply Voltage	Applied between : V <sub>UPC</sub> -V <sub>UPC</sub> , V <sub>VPC</sub> -V <sub>VPC</sub> , V <sub>N1</sub> -V <sub>N1</sub>	20	V
V <sub>CIN</sub>	Input Voltage	Applied between : U <sub>P</sub> -V <sub>UPC</sub> , V <sub>P</sub> -V <sub>VPC</sub> , U <sub>N</sub> -V <sub>N</sub> , W <sub>N</sub> -V <sub>N1</sub> , Br-V <sub>N1</sub>	20	V
V <sub>FO</sub>	Fault Output Supply Voltage	Applied between : U <sub>F</sub> -V <sub>UPC</sub> , V <sub>F</sub> -V <sub>VPC</sub> , F <sub>O</sub> -V <sub>N1</sub>	20	V
I <sub>FO</sub>	Fault Output Current	Sink current at U <sub>F</sub> , V <sub>F</sub> , F <sub>O</sub> terminals	20	mA

**PM50B6LB060**FLAT-BASE TYPE  
INSULATED PACKAGE**TOTAL SYSTEM**

Symbol	Parameter	Condition	Ratings	Unit
VCC(prot)	Supply Voltage Protected by SC	VD = 13.5 ~ 16.5V, Inverter Part, T <sub>j</sub> = +125°C Start	400	V
VCC(surge)	Supply Voltage (Surge)	Applied between : P-N, Surge value	500	V
T <sub>stg</sub>	Storage Temperature		-40 ~ +125	°C
V <sub>iso</sub>	Isolation Voltage	60Hz, Sinusoidal, Charged part to Base, AC 1 min.	2500	V <sub>rms</sub>

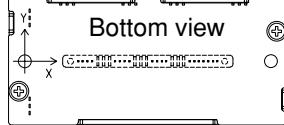
**THERMAL RESISTANCES**

Symbol	Parameter	Condition	Limits			Unit
			Min.	Typ.	Max.	
R <sub>th(j-c)Q</sub>	Junction to case Thermal Resistances	Inverter IGBT part (per 1/4 module)	(Note-1)	—	—	0.95
R <sub>th(j-c)F</sub>		Inverter FWDi part (per 1/4 module)	(Note-1)	—	—	1.61
R <sub>th(j-c)Q</sub>		Converter IGBT part	(Note-1)	—	—	0.95
R <sub>th(j-c)F</sub>		Converter FWDi upper part	(Note-1)	—	—	0.95
R <sub>th(j-c)F</sub>		Converter FWDi lower part	(Note-1)	—	—	1.61
R <sub>th(c-f)</sub>	Contact Thermal Resistance	Case to fin, (per 1 module) Thermal grease applied	(Note-1)	—	—	0.038

(Note-1) T<sub>c</sub> (under the chip) measurement point is below.

(unit : mm)

axis \ arm	UP		VP		WP	BP	UN		VN		WN		BN	
	IGBT	FWDi	IGBT	FWDi	FWDi	FWDi	IGBT	FWDi	IGBT	FWDi	IGBT	FWDi	IGBT	FWDi
X	32.7	32.2	62.8	63.3	82.9	21.8	38.8	39.3	53.0	52.5	75.6	75.1	18.1	25.9
Y	-10.0	-0.2	-8.8	-2.0	-8.4	6.8	8.0	0.8	3.8	-2.8	3.8	-2.8	-10.0	-8.4

**ELECTRICAL CHARACTERISTICS (T<sub>j</sub> = 25°C, unless otherwise noted)****INVERTER PART**

Symbol	Parameter	Condition	Limits			Unit
			Min.	Typ.	Max.	
V <sub>CE(sat)</sub>	Collector-Emitter Saturation Voltage	VD = 15V, IC = 50A	—	1.7	—	V
		VCIN = 0V (Fig. 1)	—	1.55	—	
V <sub>EC</sub>	FWDi Forward Voltage	-IC = 50A, VD = 15V, VCIN = 15V (Fig. 2)	—	2.2	3.3	V
ton	Switching Time	VD = 15V, VCIN = 0V↔15V VCC = 300V, IC = 50A T <sub>j</sub> = 125°C Inductive Load (Fig. 3,4)	0.3	0.7	1.4	μs
trr			—	0.1	0.2	
tc(on)			—	0.2	0.4	
toff			—	0.9	1.8	
tc(off)			—	0.2	0.4	
ICES	Collector-Emitter Cutoff Current	VCE = VCES, VCIN = 15V (Fig. 5)	T <sub>j</sub> = 25°C	—	1	mA
			T <sub>j</sub> = 125°C	—	10	

Jun. 2005

**CONVERTER PART**

Symbol	Parameter	Condition	Limits			Unit	
			Min.	Typ.	Max.		
VCE(sat)	Collector-Emitter Saturation Voltage	VD = 15V, IC = 50A VCIN = 0V, Pulsed (Fig. 1)	T <sub>j</sub> = 25°C T <sub>j</sub> = 125°C	— —	1.7 1.55	— —	V
V <sub>EC</sub>	FWD <sub>i</sub> Forward Voltage	—IC = 50A, VCIN = 15V, VD = 15V	(Fig. 2)	—	2.2	3.3	
V <sub>FM</sub>	Forward Voltage	IF = 50A		—	1.9	3.0	V
I <sub>CES</sub>	Collector-Emitter Cutoff Current	V <sub>CE</sub> = V <sub>CES</sub> , VD = 15V (Fig. 5)	T <sub>j</sub> = 25°C T <sub>j</sub> = 125°C	— —	— —	1 10	mA

**CONTROL PART**

Symbol	Parameter	Condition	Limits			Unit	
			Min.	Typ.	Max.		
I <sub>D</sub>	Circuit Current	VD = 15V, VCIN = 15V	V <sub>N1</sub> -V <sub>NC</sub> V <sub>P1</sub> -V <sub>PC</sub>	— —	20 5	30 10	mA
V <sub>th(ON)</sub>	Input ON Threshold Voltage	Applied between : UP-VUPC, VP-VVPC UN • VN • WN • Br-VNC	1.2	1.5	1.8		
V <sub>th(OFF)</sub>	Input OFF Threshold Voltage		1.7	2.0	2.3	V	
SC	Short Circuit Trip Level	—20 ≤ T <sub>j</sub> ≤ 125°C, VD = 15V (Fig. 3,6)	Inverter part Converter part	100 100	— —	— —	A
t <sub>off(SC)</sub>	Short Circuit Current Delay Time	VD = 15V (Fig. 3,6)	—	0.2	—	μs	
OT	Over Temperature Protection	VD = 15V	Trip level	135	145	—	°C
O <sub>Tr</sub>		Detect T <sub>j</sub> of IGBT chip	Reset level	—	125	—	
UV	Supply Circuit Under-Voltage Protection	—20 ≤ T <sub>j</sub> ≤ 125°C	Trip level	11.5	12.0	12.5	V
U <sub>VR</sub>			Reset level	—	12.5	—	
I <sub>FO(H)</sub>	Fault Output Current	VD = 15V, VFO = 15V (Note-2)	—	—	0.01	mA	
I <sub>FO(L)</sub>			—	10	15		
t <sub>FO</sub>	Minimum Fault Output Pulse Width	VD = 15V (Note-2)	1.0	1.8	—	ms	

(Note-2) Fault output is given only when the internal SC, OT & UV protections schemes of either upper or lower arm device operate to protect it.

**MECHANICAL RATINGS AND CHARACTERISTICS**

Symbol	Parameter	Condition	Limits			Unit	
			Min.	Typ.	Max.		
—	Mounting torque	Mounting part	screw : M5	2.5	3.0	3.5	N • m
—	Weight	—	—	340	—	g	

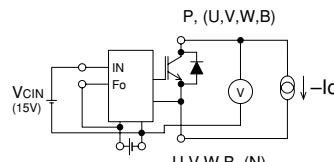
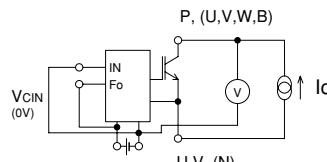
**RECOMMENDED CONDITIONS FOR USE**

Symbol	Parameter	Condition	Recommended value	Unit
V <sub>CC</sub>	Supply Voltage	Applied across P-N terminals	≤ 400	V
V <sub>D</sub>	Control Supply Voltage	Applied between : VUP-VUPC, VVP1-VVPC VN1-VNC (Note-3)	15 ± 1.5	V
V <sub>CIN(ON)</sub>	Input ON Voltage	Applied between : UP-VUPC, VP-VVPC UN • VN • WN • Br-VNC	≤ 0.8	V
V <sub>CIN(OFF)</sub>	Input OFF Voltage		≥ 9.0	
f <sub>PWM</sub>	PWM Input Frequency	Using Application Circuit of Fig. 8	≤ 20	kHz
t <sub>dead</sub>	Arm Shoot-through Blocking Time	For IPM's each input signals (Fig. 7)	≥ 2.0	μs

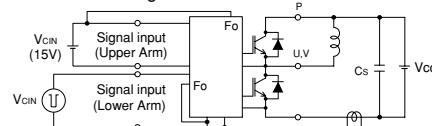
(Note-3) With ripple satisfying the following conditions : dv/dt swing ≤ ±5V/μs, Variation ≤ 2V peak to peak

## PRECAUTIONS FOR TESTING

- Before applying any control supply voltage ( $V_D$ ), the input terminals should be pulled up by resistors, etc. to their corresponding supply voltage and each input signal should be kept off state.  
After this, the specified ON and OFF level setting for each input signal should be done.
- When performing "SC" tests, the turn-off surge voltage spike at the corresponding protection operation should not be allowed to rise above  $V_{CE(SAT)}$  rating of the device.  
(These test should not be done by using a curve tracer or its equivalent.)



a) Lower Arm Switching



b) Upper Arm Switching

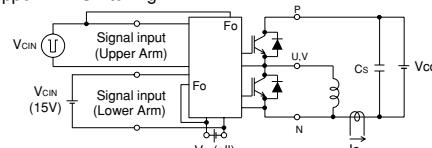


Fig. 3 Switching Time and SC Test Circuit

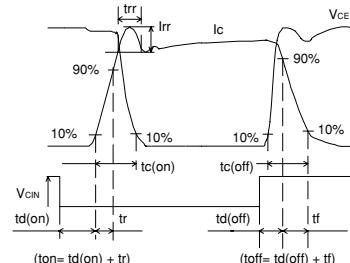


Fig. 4 Switching Time Test Waveform

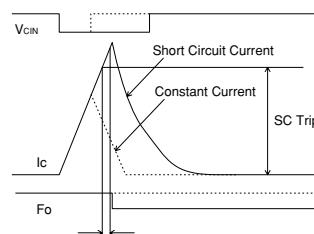
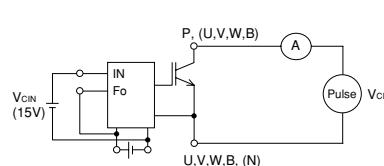


Fig. 6 SC Test Waveform

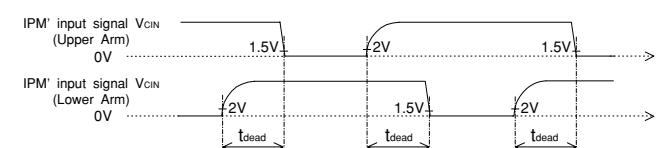
1.5V: Input on threshold voltage  $V_{th(on)}$  typical value, 2V: Input off threshold voltage  $V_{th(off)}$  typical value

Fig. 7 Dead Time Measurement Point Example

PM50B6LB060

## **FLAT-BASE TYPE INSULATED PACKAGE**

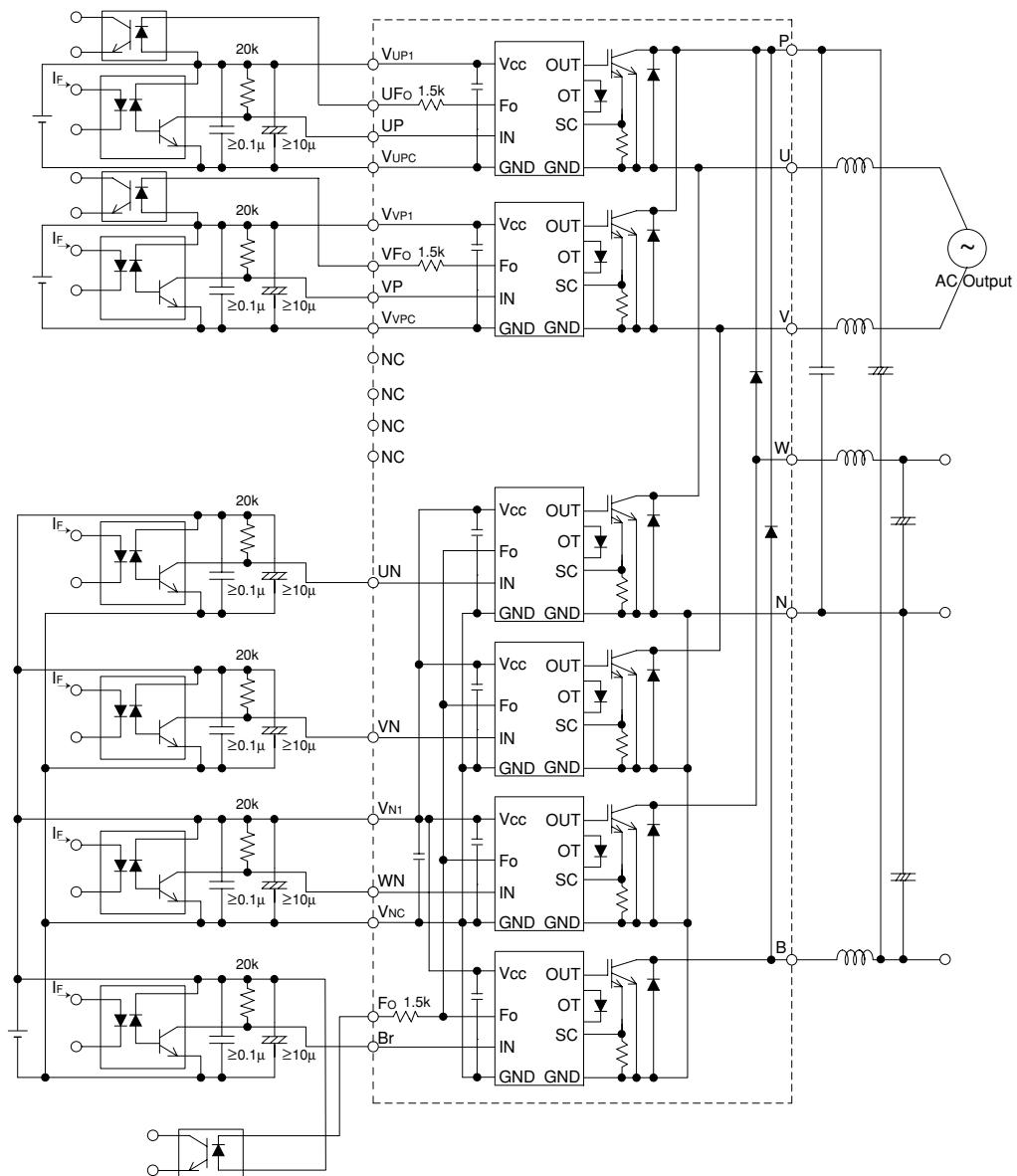
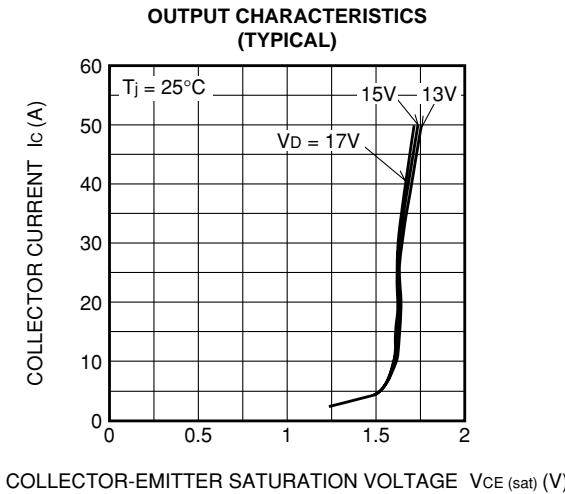
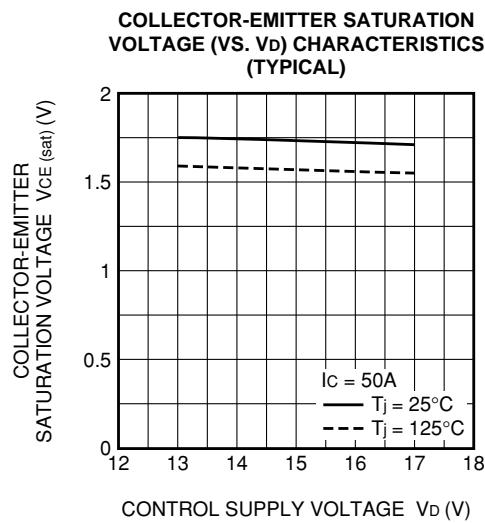
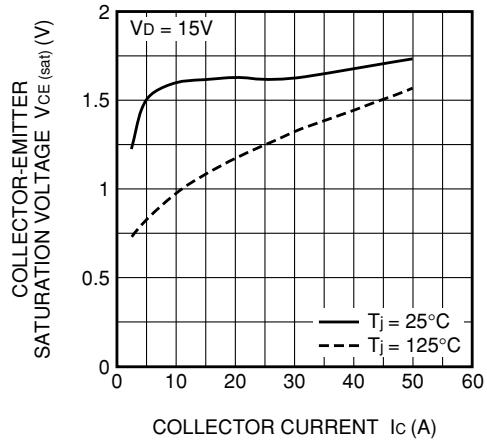
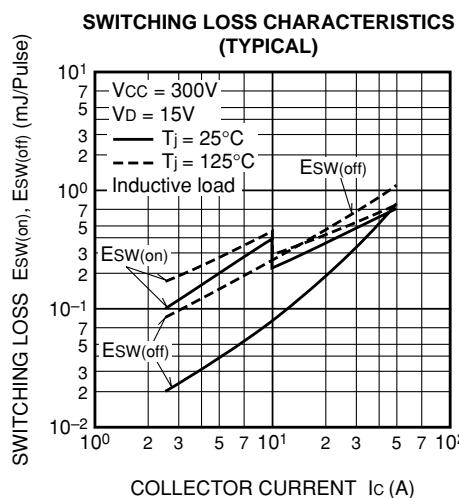
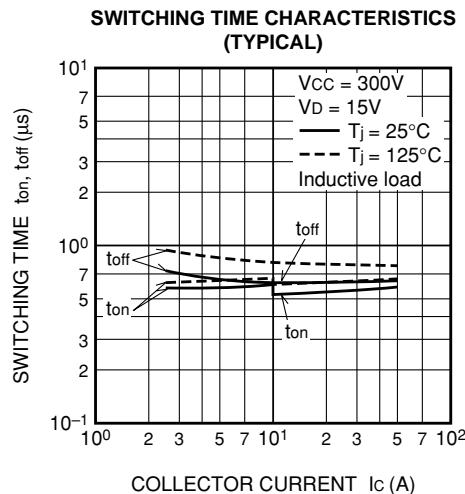
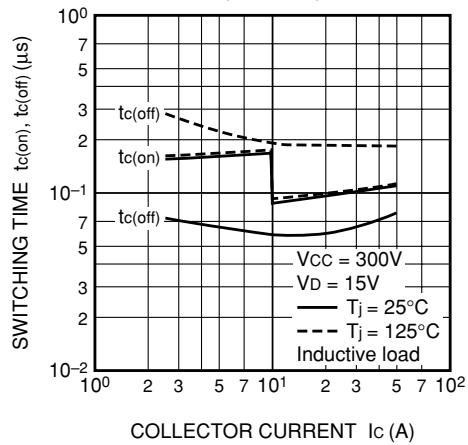
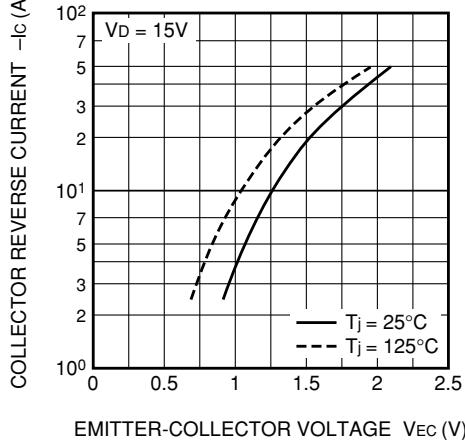
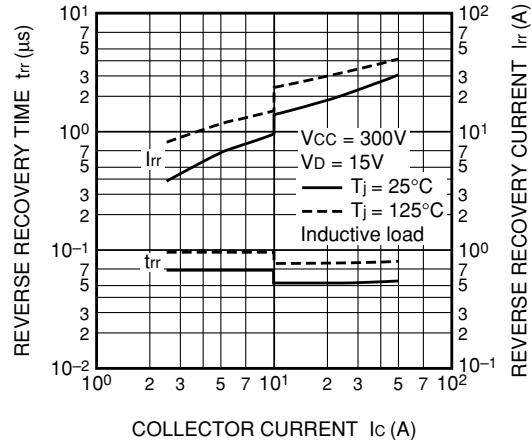
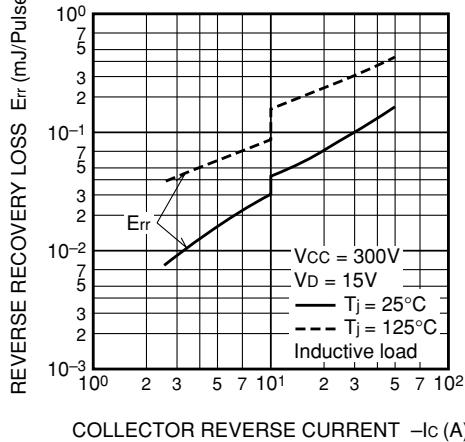
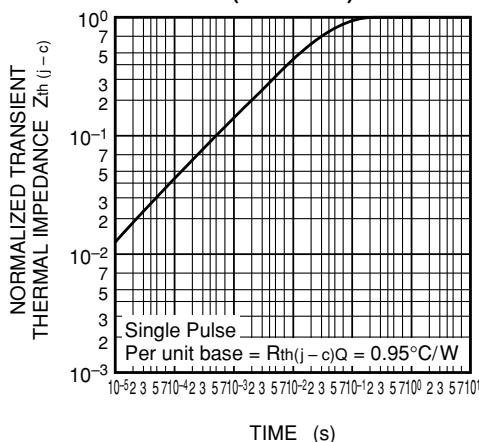
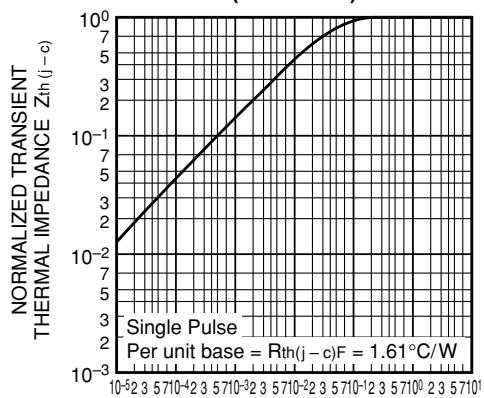


Fig. 8 Application Example Circuit

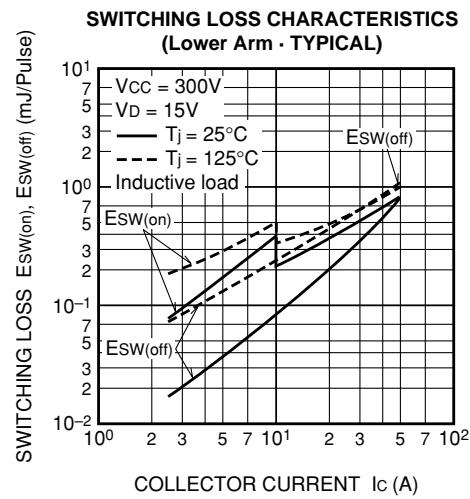
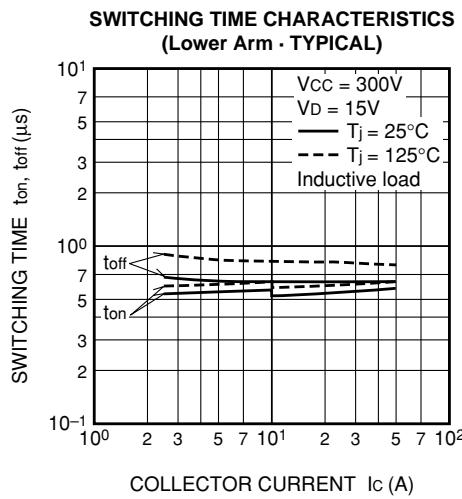
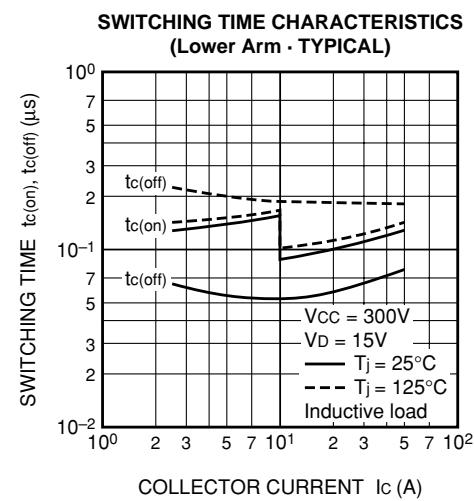
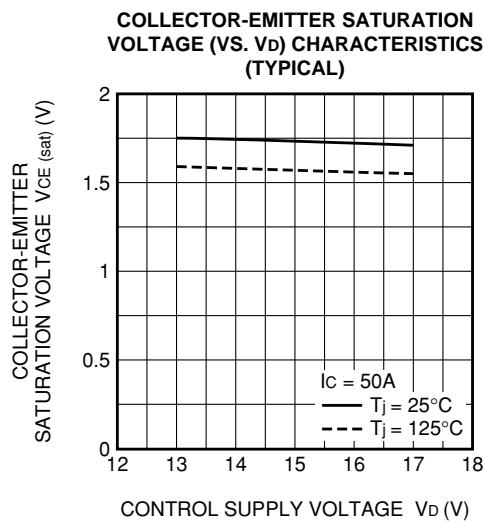
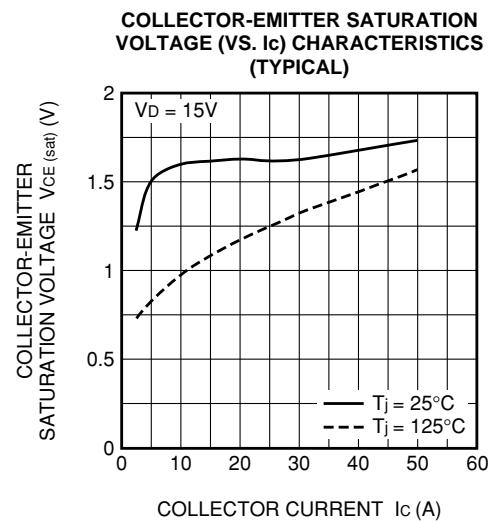
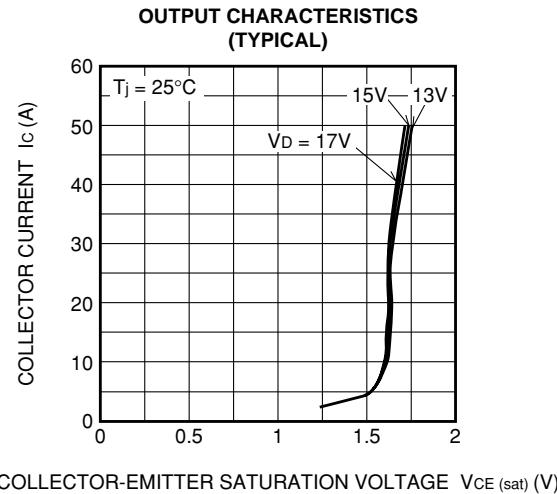
## **NOTES FOR STABLE AND SAFE OPERATION :**

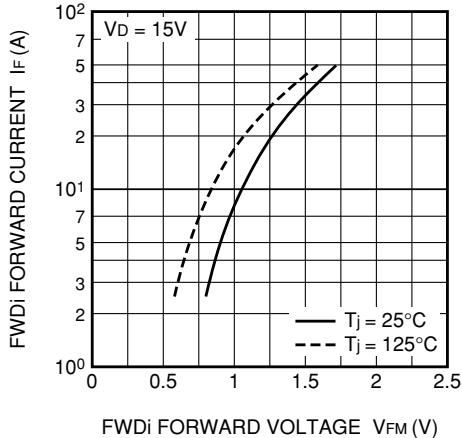
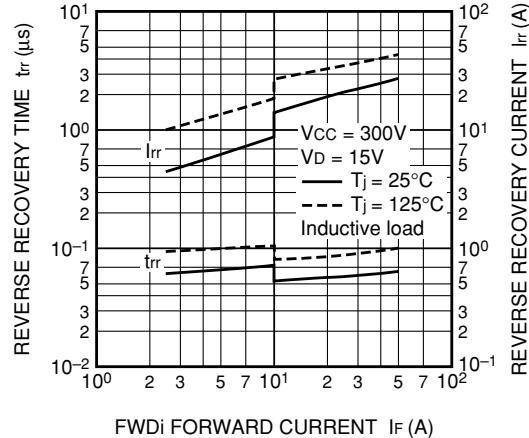
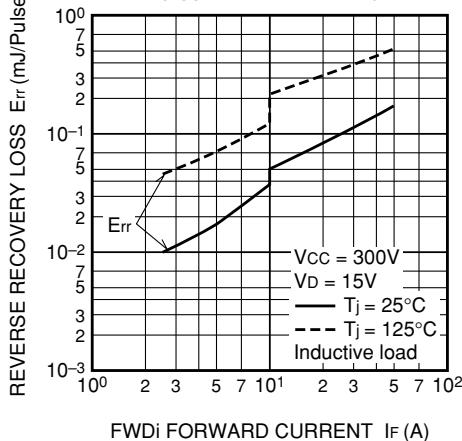
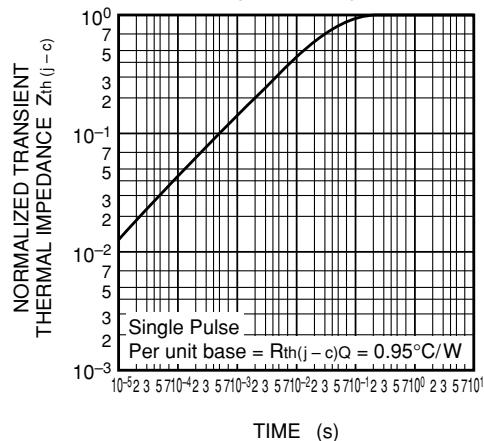
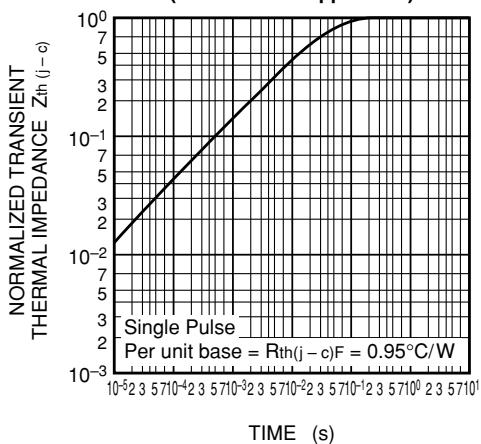
- Design the PCB pattern to minimize wiring length between opto-coupler and IPM's input terminal, and also to minimize the stray capacity between the input and output wirings of opto-coupler.
  - Connect low impedance capacitor between the Vcc and GND terminal of each fast switching opto-coupler.
  - Fast switching opto-couplers:  $t_{PLH}, t_{PHL} \leq 0.8\mu s$ , Use High CMR type.
  - Slow switching opto-coupler: CTR > 100%
  - Use 3 isolated control power supplies (Vd). Also, care should be taken to minimize the instantaneous voltage change of the power supply.
  - Make inductance of DC bus line as small as possible, and minimize surge voltage using snubber capacitor between P and N terminal.

**PERFORMANCE CURVES (INVERTER PART)****COLLECTOR-EMITTER SATURATION VOLTAGE (VS. I<sub>c</sub>) CHARACTERISTICS (TYPICAL)****SWITCHING TIME CHARACTERISTICS (TYPICAL)**

FWD<sub>i</sub> FORWARD VOLTAGE CHARACTERISTICS  
(TYPICAL)FWD<sub>i</sub> REVERSE RECOVERY CHARACTERISTICS  
(TYPICAL)FWD<sub>i</sub> REVERSE RECOVERY LOSS CHARACTERISTICS  
(TYPICAL)TRANSIENT THERMAL  
IMPEDANCE CHARACTERISTICS  
(IGBT PART)TRANSIENT THERMAL  
IMPEDANCE CHARACTERISTICS  
(FWD<sub>i</sub> PART)

## (CONVERTER PART)



FWD<sub>i</sub> FORWARD VOLTAGE CHARACTERISTICS  
(Upper Arm · TYPICAL)FWD<sub>i</sub> REVERSE RECOVERY CHARACTERISTICS  
(Upper Arm · TYPICAL)FWD<sub>i</sub> REVERSE RECOVERY LOSS CHARACTERISTICS  
(Upper Arm · TYPICAL)TRANSIENT THERMAL  
IMPEDANCE CHARACTERISTICS  
(IGBT PART)TRANSIENT THERMAL  
IMPEDANCE CHARACTERISTICS  
(FWD<sub>i</sub> PART · Upper Arm)TRANSIENT THERMAL  
IMPEDANCE CHARACTERISTICS  
(FWD<sub>i</sub> PART · Lower Arm)